

CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS

INTERCONNECT

Applicant: Erik W. Jensen

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The paragraph beginning at page 3, line 20.

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Figure 1A is a top view of one embodiment of an interconnect 100 according to the teachings of the present invention. As can be seen in Figure 1A, the interconnect 100 is formed on a substrate 101. The interconnect 100 includes a pad 102 and three vias 104-106 coupled to the pad 102. The via 104 is coupled to the pad 102 by a conductive segment 110. The via 105 is coupled to the pad 102 by a conductive segment 112. The via 106 is directly coupled to the pad 102. To directly couple the via 106 to the pad 102, after the via 106 is formed in the substrate 101, the pad 102 is formed substantially over the via 106 such that the via 106 is physically and electrically coupled to the pad 102.